

IEEE 802.3cg 10SPE TF/802.3 10BPE SG AdHoc meeting December 20th, 2017

Prepared by Peter Jones

Proposed Agenda:

1. Agenda/Admin Peter Jones

Presentations posted at:

<http://www.ieee802.org/3/cg/public/adhoc/index.html>

Agenda/Admin Peter Jones:

Meeting began at 7:05am PT.

1. Reviewed the Attendance information related to the ad hoc(s).
2. Displayed pre & post-par slide deck, reviewed patent policy, participation conditions.
<https://development.standards.ieee.org/myproject/Public/mytools/mob/preparslides.pdf> (10BP)
<https://development.standards.ieee.org/myproject/Public/mytools/mob/slideset.ppt> (10SPE)
<https://mentor.ieee.org/802-ec/dcn/17/ec-17-0093-05-OPNP-ieee-802-participation-slide-ppt.ppt>
3. Made potentially essential patents call for 802.3cg – 10SPE
No-one responded.
4. Reminded participants to indicate full names and employer/affiliations correctly for the meeting minutes.
5. Approved November 22 and December 06 minutes

Presentations/Discussion.

Start and Administrivia

Proposed PAR, CSDs and Objectives Changes

Peter Jones Cisco
George Zimmerman CME(*)

- Slides presented and discussed.
- Notes recorded on slides during meeting – update to be posted.
- Changes/issues/concerns to be discussed on & off the reflector before the next AdHoc meeting Jan 3rd.

Open issues on the D1.0 1000m link specification

Dieter Schicketanz consultant Reutlingen University

- Slides presented and discussed.

New Preamble Proposal for 10BASE-T1S

Jay Cordaro Broadcom

- Slides presented and discussed.

Line Coding Considerations for 10BASE-T1S

Jay Cordaro Broadcom

- Slides presented and discussed.

Meeting closed – ~9:00a PT

Attendees (from Webex + emails)

Name	Employer	Affiliation	Attended 12/20
Amrik Bains	Cisco	Cisco	y
Bob Voss	Panduit	Panduit	y
Brett McClellan	Marvell	Marvell	y
Brian Franchuck	Emerson	Emerson	y
Brian Jaroszewski	Microsemi	Microsemi	y
Bryan Moffitt	CommScope	CommScope	y
Chris Diminico	MC Communications/Panduit	MC Communications/Panduit	y
Conrad Zerna	Fraunhofer IIS	Fraunhofer IIS	y
Dale Borgeson	ED Engineering	Emerson	y
David Brandt	Rockwell Automation	Rockwell Automation	y
David Law	HPE	HPE	y
Dayin Xu	Rockwell Automation	Rockwell Automation	y
Dieter Schicketanz	Consultant, Reutlingen University	Consultant, Reutlingen University	y
Eric DiBiaso	TE	TE	y
Fatma Caliskan	Microchip	Microchip	y
Geet Modi	TI	TI	y
Geoff Thompson	GraCaSI S.A.	Independent	y
George Zimmerman	CME Consulting	ADI, Aquantia, BMW, Cisco, Commscope	y
Gergely Huszak	Kone	Kone	y
Harald Zweck	Infineon	Infineon	y
Hongming An	Microchip	Microchip	y
Jay Cordaro	Broadcom	Broadcom	y
Jean Picard	TI	TI	y
Jens Gottron	Siemens	Siemens	y

Jim Bauer	Marvell	Marvell	y
John Yurtin	Aptiv	Aptiv	y
Jon Lewis	Dell	Dell	y
Laura Schweitz	Turck	Turck	y
Mandeep Chadha	MicroSemi	MicroSemi	y
Mario Traeber	Intel	Intel	y
Masood Shariff	CommScope	CommScope	y
Mathias Adam	MicroChip	MicroChip	y
Matthias Fritsche	HARTING Electronics GmbH	HARTING Electronics GmbH	y
Nicola Scantamburlo	Canova Tech	Canova Tech	y
Peter Jones	Cisco	Cisco	y
Piergiorgio Beruto	Canova Tech	Canova Tech	y
Robert Moskowitz	HTT Consulting	HTT Consulting	y
Scott Sommers	Molex	Molex	y
Steffen Graber	Pepperl+Fuchs	Pepperl+Fuchs	y
Sujan Pandey	NXP	NXP	y
Thomas Mueller	Rosenberger	Rosenberger	y
Tim Baggett	Microchip	Microchip	y
Valerie Maguire	Siemon	Siemon	y
Attendee count			43